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IGBT

SGH80N60UFD

Ultrafast IGBT

General Description

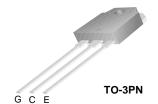
Fairchild's UFD series of Insulated Gate Bipolar Transistors (IGBTs) provides low conduction and switching losses. The UFD series is designed for applications such as motor control and general inverters where high speed switching is a required feature.

Features

- High speed switching
- Low saturation voltage : $V_{CE(sat)} = 2.1 \text{ V } @ I_C = 40 \text{A}$
- · High input impedance
- CO-PAK, IGBT with FRD : t_{rr} = 50ns (typ.)

Applications

AC & DC motor controls, general purpose inverters, robotics, and servo controls.





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

| Symbol | Description | | SGH80N60UFD | Units |
|---------------------|--|--------------------------|-------------|-------|
| V _{CES} | Collector-Emitter Voltage | | 600 | V |
| V _{GES} | Gate-Emitter Voltage | | ± 20 | V |
| | Collector Current | @ T _C = 25°C | 80 | А |
| I _C | Collector Current | @ T _C = 100°C | 40 | А |
| I _{CM (1)} | Pulsed Collector Current | | 220 | Α |
| I _F | Diode Continuous Forward Current | @ T _C = 100°C | 25 | А |
| I _{FM} | Diode Maximum Forward Current | | 280 | Α |
| P _D | Maximum Power Dissipation | @ T _C = 25°C | 195 | W |
| | Maximum Power Dissipation | @ T _C = 100°C | 78 | W |
| T _J | Operating Junction Temperature | | -55 to +150 | °C |
| T _{stg} | Storage Temperature Range | | -55 to +150 | °C |
| T _L | Maximum Lead Temp. for Soldering Purposes,/8" from Case for 5 Seconds | | 300 | °C |

Notes:(1) Repetitive rating: Pulse width limited by max. junction temperature

Thermal Characteristics

| Symbol | Parameter | Тур. | Max. | Units |
|---|--------------------------------------|------|------|-------|
| $R_{\theta JC}(IGBT)$ | Thermal Resistance, Junction-to-Case | | 0.64 | °C/W |
| R ₀ JC(DIODE) Thermal Resistance, Junction-to-Case | | | 0.83 | °C/W |
| R _{θJA} Thermal Resistance, Junction-to-Ambient | | | 40 | °C/W |

| Symbol | Parameter | Test Conditions | Min. | Тур. | Max. | Units |
|--|---|--|------|--------------------|-----------------|----------------------|
| Off Cha | racteristics | | | | | |
| BV _{CES} | Collector-Emitter Breakdown Voltage | V _{GE} = 0V, I _C = 250uA | 600 | | | V |
| $\Delta B_{VCES}/$ ΔT_J | Temperature Coefficient of Breakdown Voltage | $V_{GE} = 0V$, $I_C = 1mA$ | | 0.6 | | V/°C |
| I _{CES} | Collector Cut-Off Current | $V_{CE} = V_{CES}, V_{GE} = 0V$ | | | 250 | uA |
| I_{GES} | G-E Leakage Current | $V_{GE} = V_{GES}, V_{CE} = 0V$ | | | ± 100 | nA |
| On Cha | racteristics | | | | | |
| V _{GE(th)} | G-E Threshold Voltage | $I_C = 40 \text{mA}, V_{CE} = V_{GE}$ | 3.5 | 4.5 | 6.5 | V |
| | Collector to Emitter | $I_C = 40A$, $V_{GE} = 15V$ | | 2.1 | 2.6 | V |
| $V_{CE(sat)}$ | Saturation Voltage | $I_{C} = 80A, V_{GE} = 15V$ | | 2.6 | | V |
| Dvnami | c Characteristics | | | | | |
| C _{ies} | Input Capacitance | | | 2790 | | pF |
| C _{oes} | Output Capacitance | $V_{CE} = 30V, V_{GE} = 0V,$ | | 350 | | pF |
| C _{res} | Reverse Transfer Capacitance | f = 1MHz | | 100 | | pF |
| | ng Characteristics | T | | 00 | | |
| t _{d(on)} | Turn-On Delay Time | - | | 23 | | ns |
| t _r | Rise Time | ., | | 50 | | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 300 \text{ V}, I_{C} = 40\text{A},$ | | 90 | 130 | ns |
| t _f | Fall Time | $R_G = 5\Omega$, $V_{GE} = 15V$, Inductive Load, $T_C = 25^{\circ}C$ | | 50 | 150 | ns |
| E _{on} | Turn-On Switching Loss Turn-Off Switching Loss | madelive Load, TC = 25 C | | 570 590 | | uJ uJ |
| E _{off} | Total Switching Loss | - | | 1160 | 1500 | uJ |
| E _{ts} | Turn-On Delay Time | | | 30 | | ns |
| t _{d(on)} t _r | Rise Time | - | | 55 | | ns |
| t _{d(off)} | Turn-Off Delay Time | $V_{CC} = 300 \text{ V}, I_{C} = 40\text{A},$ | | 150 | 200 | ns |
| *u(OII) | Fall Time | $R_G = 5\Omega$, $V_{GE} = 15V$, | | 160 | 250 | ns |
| | | | | | | |
| t _f | | | | 630 | | |
| t _f E _{on} | Turn-On Switching Loss | Inductive Load, T _C = 125°C | | 630 940 | | uJ |
| t _f E _{on} E _{off} | Turn-On Switching Loss Turn-Off Switching Loss | | | | | |
| t _f E _{on} E _{off} E _{ts} | Turn-On Switching Loss | Inductive Load, T _C = 125°C | | 940 | | uJ uJ |
| t_f E_{on} E_{off} E_{ts} Q_g | Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss | Inductive Load, $T_C = 125$ °C $V_{CE} = 300 \text{ V}, I_C = 40\text{A},$ | | 940 1580 | 2000 | uJ uJ uJ |
| t _f E _{on} E _{off} E _{ts} | Turn-On Switching Loss Turn-Off Switching Loss Total Switching Loss Total Gate Charge | Inductive Load, T _C = 125°C | | 940 1580 175 | 2000 250 | uJ uJ uJ nC |

Electrical Characteristics of DIODE $T_C = 25^{\circ}C$ unless otherwise noted

| Symbol | Parameter | Test Conditions | | Min. | Тур. | Max. | Units |
|-----------------|---|--|------------------------|------|------|------|-------|
| V | Diode Forward Voltage | I _F = 25A | $T_C = 25^{\circ}C$ | | 1.4 | 1.7 | V |
| V_{FM} | Diode Forward Voltage | IF = 25A | T _C = 100°C | | 1.3 | | V |
| | t _{rr} Diode Reverse Recovery Time | I _F = 25A, di/dt = 200A/us | $T_C = 25^{\circ}C$ | | 50 | 95 | no |
| ^L rr | | | T _C = 100°C | | 105 | | ns |
| | Diode Peak Reverse Recovery | | $T_C = 25^{\circ}C$ | | 4.5 | 10 | Α |
| ^I rr | Current | | T _C = 100°C | | 8.5 | | A |
| | Diode Reverse Recovery Charge | | $T_C = 25^{\circ}C$ | | 112 | 375 | ~C |
| Q_{rr} | | | T _C = 100°C | | 420 | | nC |

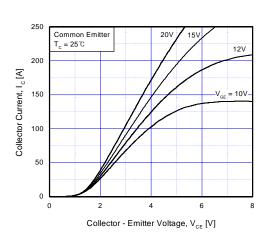


Fig 1. Typical Output Characteristics

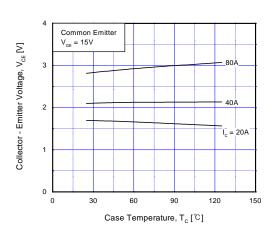


Fig 3. Saturation Voltage vs. Case Temperature at Variant Current Level

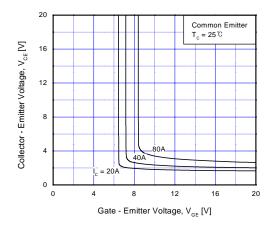


Fig 5. Saturation Voltage vs. V_{GE}

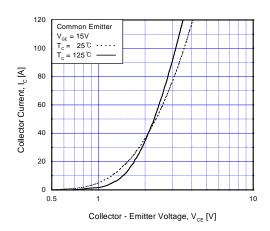


Fig 2. Typical Saturation Voltage Characteristics

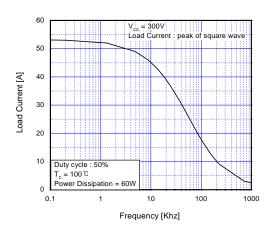


Fig 4. Load Current vs. Frequency

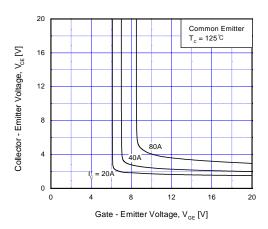
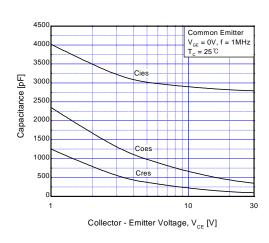


Fig 6. Saturation Voltage vs. $V_{\rm GE}$



Switching Time [ns] 20

Common Emitter

T_c = 125℃ · · · · ·

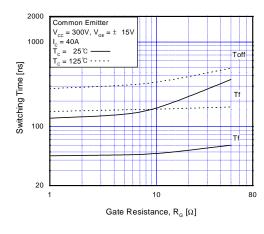
 $V_{cc} = 300V, V_{GE} = \pm 15V$ $I_{c} = 40A$ $T_{c} = 25^{\circ}C$

500

Fig 7. Capacitance Characteristics

Fig 8. Turn-On Characteristics vs. **Gate Resistance**

Gate Resistance, $R_{_{\rm G}}\left[\Omega\right]$



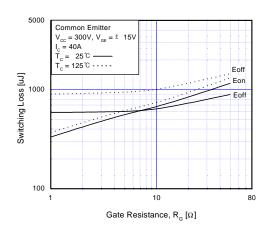
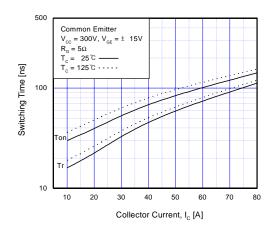


Fig 9. Turn-Off Characteristics vs. **Gate Resistance**

Fig 10. Switching Loss vs. Gate Resistance



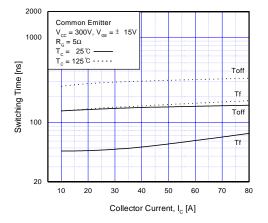
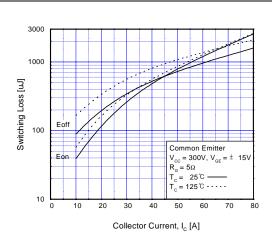


Fig 11. Turn-On Characteristics vs. **Collector Current**

Fig 12. Turn-Off Characteristics vs. **Collector Current**



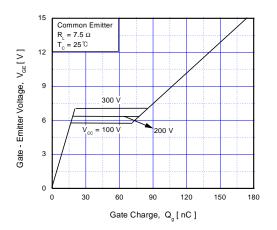
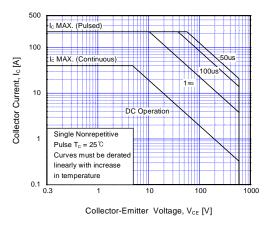


Fig 13. Switching Loss vs. Collector Current

Fig 14. Gate Charge Characteristics



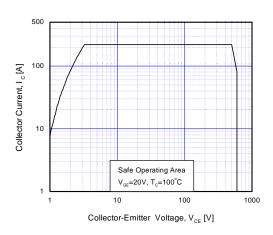


Fig 15. SOA Characteristics

Fig 16. Turn-Off SOA Characteristics

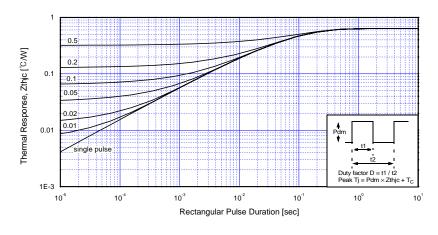
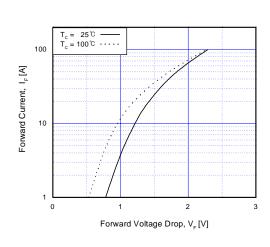


Fig 17. Transient Thermal Impedance of IGBT



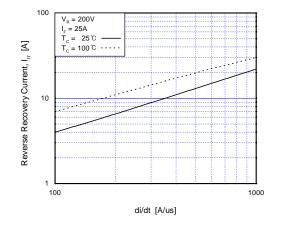
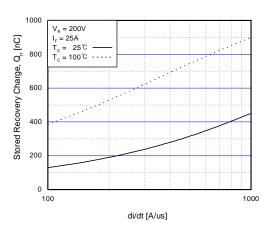


Fig 18. Forward Characteristics

Fig 19. Reverse Recovery Current



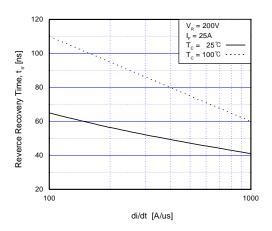
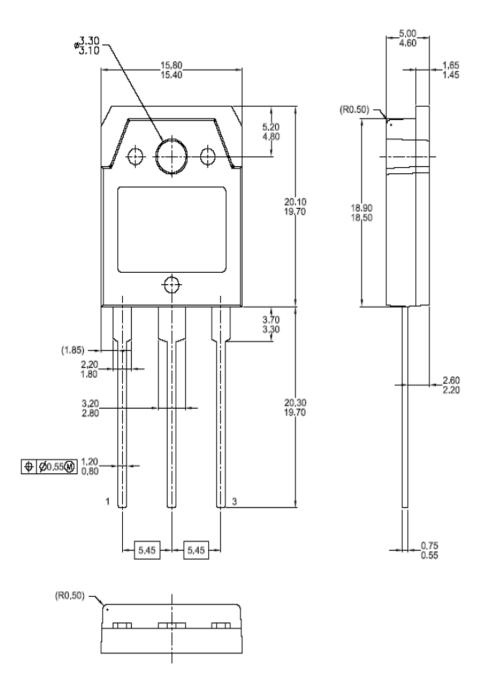


Fig 20. Stored Charge

Fig 21. Reverse Recovery Time



TO-3PN



Dimensions in Millimeters

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